







Click here for the 3D model.

Dimensions	
D	25.64mm +/-0.635mm
L	6.35mm MIN
Н	2.54mm NOM
F	1.397mm +/-0.25mm
Α	10.67mm MAX
В	12.448mm MAX
С	11.43mm +/-0.635mm
Е	12.7mm MAX
K	0.5mm NOM

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	16

General Information			
Series	KPS-MCC Indust COG HT200C		
Style	Leaded Stacked Chip		
Description	Low ESR, Stacked Ceramic Chips		
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance		
RoHS	No		
Prop 65	▲ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov.		
Termination	60/40 Solder Coated		
Lead	Straight Leads		
AEC-Q200	No		
Notes	Number of chips in this stack: 8.		

KPS-MCC Indust COG HT200C, Ceramic, 1.6 uF, 10%, 500 VDC, COG

Specifications	
Capacitance	1.6 uF
Capacitance Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	650 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	630 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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>>KEMET(基美)